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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: : Yong-Bae Kim and Philippe Schoenborn
Appl. No. : Continuation of 09/898,194
Filed: : Herewith
Title : PROCESS FOR REMOVAL OF PHOTORESIST MASK USED FOR
MAKING VIAS IN LOW K CARBON-DOPED SILICON OXIDE
DIELECTRIC MATERIAL, AND FOR REMOVAL OF ETCH
RESIDUES FROM FORMATION OF VIAS AND REMOVAL OF
PHOTORESIST MASK

Grp./ A.U. : 1765
Examiner : Kin-Chan Chen
Docket No. : 01-125/1C

PRELIMINARY AMENDMENT

**Honorable Commissioner for Patents
Post Office Box 1450
Alexandria, VA 22313-1450**

Date: July 14, 2003

Sir:

Please amend the accompanying continuation application as follows: